

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC90N10S5N062	**Issued**	7. January 2020
MA#	MA005346297		
Package	PG-TDSON-8-34	**Weight***	112.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.447	1.28	1.28	12813	12813
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		469	
	non noble metal	copper	7440-50-8	52.842	46.80	46.86	467982	468592
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		661	
	plastics	epoxy resin	-	5.894	5.22		52197	
	inorganic material	silicondioxide	60676-86-0	31.334	27.75	33.04	277504	330362
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13938	13938
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1853	1853
solder	non noble metal	tin	7440-31-5	0.033	0.03		289	
	noble metal	silver	7440-22-4	0.041	0.04		361	
	non noble metal	lead	7439-92-1	1.557	1.38	1.45	13792	14442
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.90	14.91	149029	149223
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5659	5659
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2741	2745
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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